

## PD955 M

### SMT Adhesive

#### Description

PD955 M is a thermosetting single component, solvent-free polymer adhesive, developed especially for the surface mounting of SMT components onto PCBs and for use on bare substrates. This rheology is specially adapted for high-speed dispensing.

#### Key Features

- Very wide processing window, no tendency towards stringing
- Excellent adhesion with standard and also with difficult to glue components
- Consistent batch-to-batch quality



*This picture does not show the packaging of PD955 M and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Physical Properties

|                                     |  |
|-------------------------------------|--|
| Processing time at 20 – 30°C (days) | Max. 2   |
| Curing Profile                      | The standard curing conditions are 125°C / 3 minutes. As long as the curing profile is respected, the adhesive can withstand reflow conditions according IPC/JEDEC J-STD-020<br><br>1 min / 180 °C<br>1,5 min / 150 °C<br>3 min / 125 °C<br>8 min / 100 °C |
| Color                               | Red  |
| Applications                        | Dispensing   |

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#### Adhesive Conditioning

- Remove adhesive from fridge: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open cartridge while adhesive is cold to prevent condensation
- Before using adhesive cartridge: Before inserting nozzle, press small quantity of glue out of cartridge until homogeneous glue comes out – during storage of cartridges, low viscosity glue constituents may be found on the tip of the cartridge

#### Cleaning Instructions

**Before curing:** The adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. Do not use alcohol as this will cure the adhesive. Cleaned dispensing units should be completely dried before installation.

**After Curing:** Defective components can be replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.

#### Storage Conditions

- Store the SMT-adhesive in originally sealed containers and avoid exposure to high humidity and sunlight
- Store cartridges with tip pointing downwards
- Max. expiration date: Shelf life: Please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 – 10 °C

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